

Procedural Review Voting Sheet

Editorial Change(s) to a published Standard or Safety Guideline (Independently from a Letter Ballot)

REGION/LOCALE: **North America**

GLOBAL TECHNICAL COMMITTEE: **3D Packaging & Integration**

EVENT: **NA Summer Meetings**

DATE OF MEETING: **07/15/2021**

PLACE OF MEETING: **OVTCCM**

TC CHAPTER CO-CHAIRS: **Bill Kerr/Evergreen Enhancement, Chris Moore/Covalent Metrology**

SEMI STANDARDS STAFF: **Laura Nguyen**

I. Document Title

Document Title

SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications

II. Type 2 Editorial Change

Editorial changes that meet the requirements of the Regulations (see *Regulations* ¶¶ 8.9.4 & 8.9.5) are approved by a simple majority vote in a regularly scheduled meeting of the TC Chapter. [See PM 2.11.4]

Original section/paragraph number and at least one full sentence are required in “FROM” and “TO” fields.

FROM: Section/Paragraph 4, Footnote 3, Table 1, 13

4 Referenced Standards and Documents

4.1 *SEMI Standards and Safety Guidelines*

SEMI G90 — Specification for 300 mm Coin-Stack Type Shipping Container Used for Test and Packaging Processes

SEMI M31 — Mechanical Specification for Front-Opening Shipping Box Used to Transport and Ship 300 mm Wafers

4.4 *JEITA Standard*⁴

JEITA EM-3401 — Terminology of Silicon Wafer Flatness

Footnote #3

³Japan Electronics and Information Technology Industries Association, Ote Center Building, 1-1-3, Otemachi, Chiyoda-ku, Tokyo 100-0004, Japan; <http://www.jeita.or.jp>

Table 1, Part 2 (2-11)

☐ SEMI 3D12

☐ SEMI MF1451

☐ JEITA EM-3401

☐ Other: _____

9.1 Measurements shall be made or certifiable to one of the SEMI, ASTM, JEITA, or JIS standard test methods for the item selected from Specification Ordering Table and specified in the purchase order.

13 Related Documents

13.1 *SEMI Standards and Safety Guidelines*

SEMI M1 — Specifications for Polished Single Crystal Silicon Wafers

1 TO: Section/Paragraph 4, Footnote 3, Table 1, 13

4 Referenced Standards and Documents

4.1 *SEMI Standards and Safety Guidelines*

SEMI G90 — Specification for 300 mm [Wafer](#) Coin-Stack Type Shipping Container Used for Test and Packaging Processes

SEMI M31 — ~~Mechanical~~ Specification for [Mechanical Features of](#) Front-Opening Shipping Box Used to Transport and Ship 300 mm Wafers

~~4.4 JEITA Standard~~⁴

~~JEITA EM 3401 — Terminology of Silicon Wafer Flatness~~

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13 Related Documents

13.1 *SEMI Standards and Safety Guidelines*

SEMI M1 — Specification~~s~~ for Polished Single Crystal Silicon Wafers

	Justification: (If necessary) JEITA EM-3401 no longer exists. All instances referring to JEITA should be deleted. (Delete Footnote #3) Fix outdated titles in Referenced Standards and Documents section.
Motion	To approve the above editorial change(s).
Motion by/ 2nd by	By: Richard Allen / NIST - National Institute of Standards & Technology Second: Steve Martell / Nordson SONOSCAN
Discussion	None
Vote	6 Y 0 N ; If Y > 50% Motion passes, GO TO III

III. Safety Check

Note: See Regulations § 15 for further information.

Motion	X	This is not a Safety Document , when all safety-related information is removed, the Document is still technically sound and complete. (<i>Regulations ¶ 8.7.1</i>)
		This is a Safety Document , when all safety-related information is removed, the Document is not technically sound and complete. (<i>Regulations ¶ 8.7.2</i>)
		Safety Checklist (<i>Regulations ¶ 15.3</i>) is complete and has been included with the Document throughout the balloting process. (<i>Regulations ¶ 15.1.2</i>)
Motion by/2nd by		By: Ilona Schmidt / Corning Inc. Second: Gregory Arslanian / Air Products
Discussion		None
Vote		6 Y 0 N; Motion passed.

IV. Intellectual Property Check

Note: This Document may cover all or part of a Standard or Safety Guideline. Regardless of the coverage, this IP check applies to the entire Standard or Safety Guideline*. See *Regulations* § 16 for further information.

X	The TC Chapter meeting chair asked those participating, if they were aware of any patented technology that might be relevant (see <i>Regulations</i> ¶ 16.3.1.1) to the Standard or Safety Guideline; or, any copyrighted items or trademarks that are used/reproduced (see <i>Regulations</i> ¶ 16.4.1.2) in the Standard or Safety Guideline. (Also see, <i>Regulations</i> § 8.8)		
	X	The question is NOT answered in affirmative (No potentially material patented technology or use/reproduction of copyrighted items/trademarks is known.)	GO TO SECTION V.

V. Action for this Document

Motion	X	This Editorial Change Type 2 passed TC Chapter review and will be forwarded to the ISC A&R SC for procedural review.	
Motion by/ 2nd by		By: Steve Martell / Nordson SONOSCAN Second: Gregory Arslanian / Air Products	
Discussion		None	
Vote		6 Y 0 N; Motion passed.	
Final Action		X	Motion passed
			Motion failed